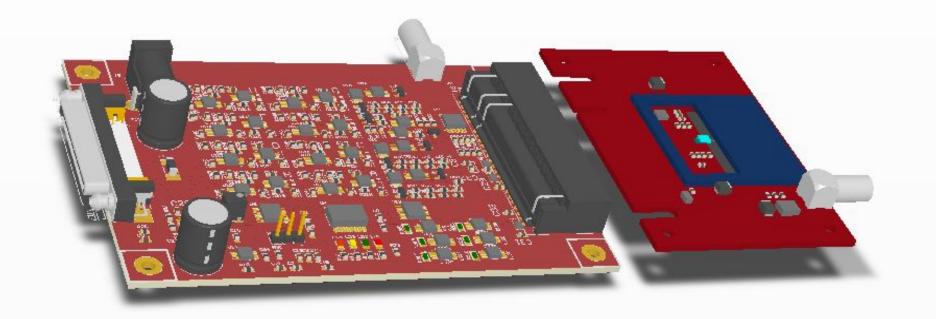
CCPDV3 & CLICpix readout status





Szymon Kulis CLICdp Collaboration Meeting, 11/06/2014, CERN

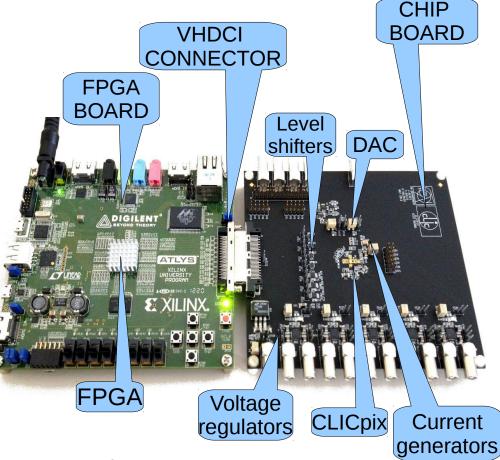
CLICpix readout

CLICpix

- Configuration: several 8 bit registers + matrix configuration 24kB
- Data transition custom serial interface
 @ 320 MHz

CLICpix readout

 Readout is ready (was used for chip parametrization)





Proposition of new readout system

FPGA (Atlys board)

Interface board

- voltage regulators (with monitoring)
- current generators
- level translators
- ADC / DAC

CHIP under test

(decoupling capacitors)







PCI Express



11/06/2014

Pros of new modular readout scheme

- Easier calibration of on board voltage references, current references, power supplies (one calibration per readout system, not one per chip)
- Cheaper
 - Chip board is very simple, almost no components (reduces also cabling cost)
 - No expensive connector on each chip board
 - Appropriate technology can be used for each PCB (more layers for interface board, higher precision for chip board)
- Swapping chips is very easy & fast (electrical calibration stays the same)



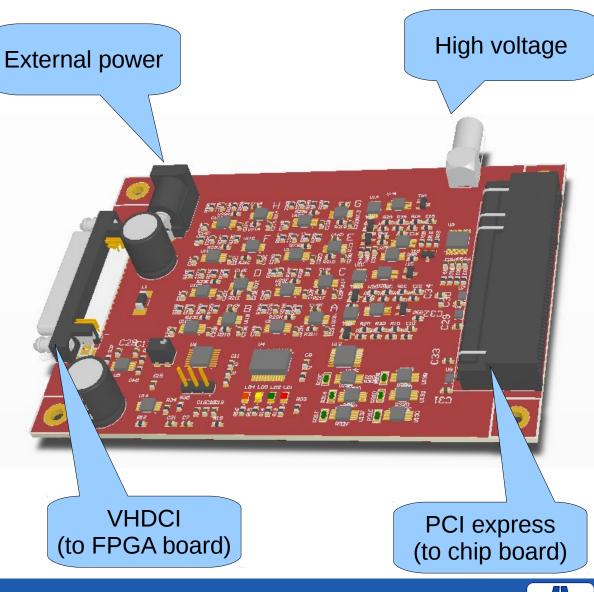
Interface board

Analog

- 8 x general purpose power supply
- 4 x voltage outputs)
- 4 x current outputs
- 4 x voltage inputs
- High voltage input

Digital

- 12 x general CMOS signals (Input / Output)
- 12 x differential pairs | (Input / Output)
- I²C bus
- Status LEDs

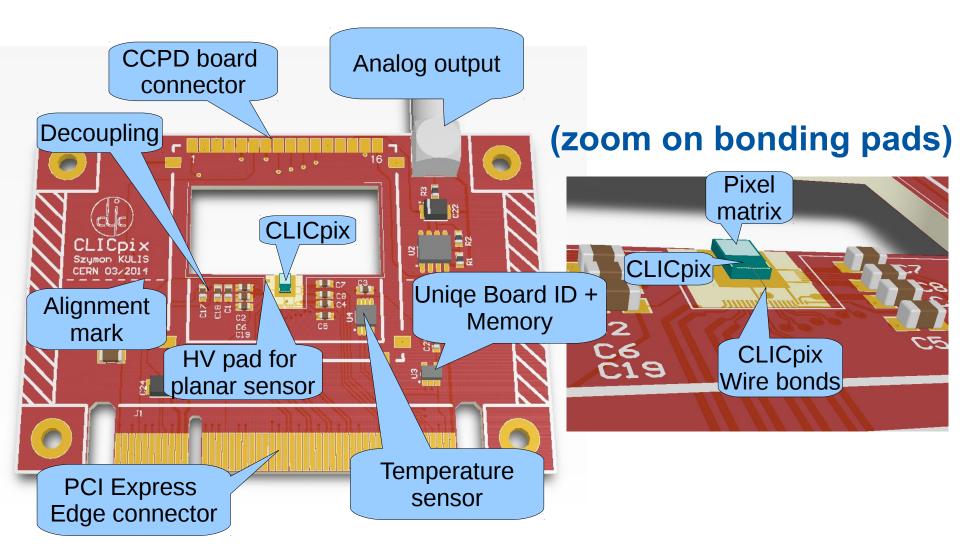




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CLICpix chip board

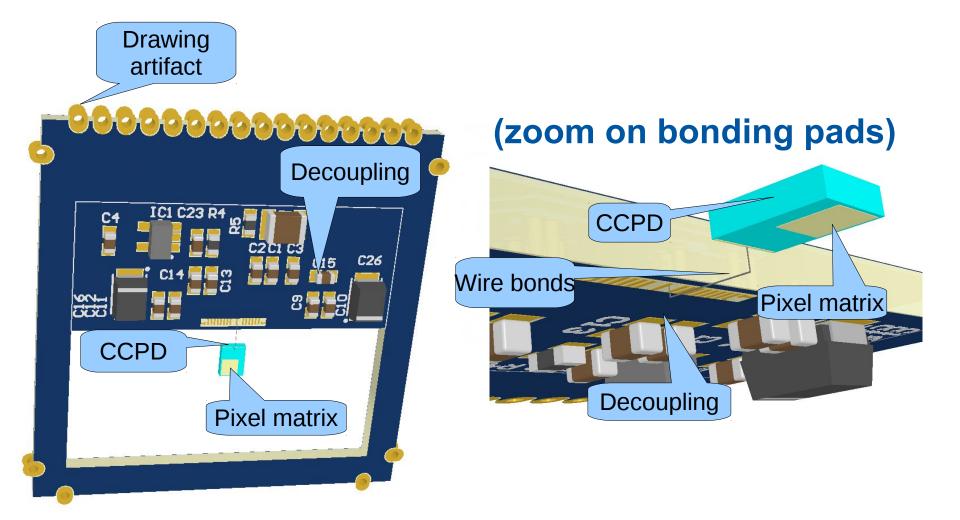


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CCPD chip board (bottom side view)



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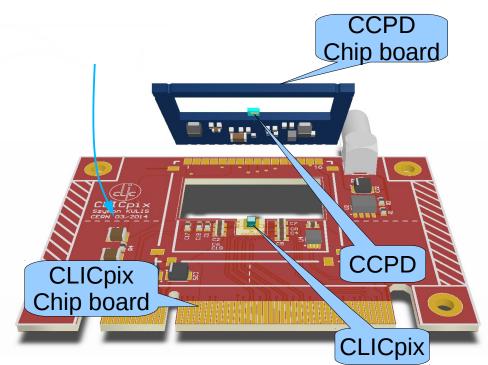
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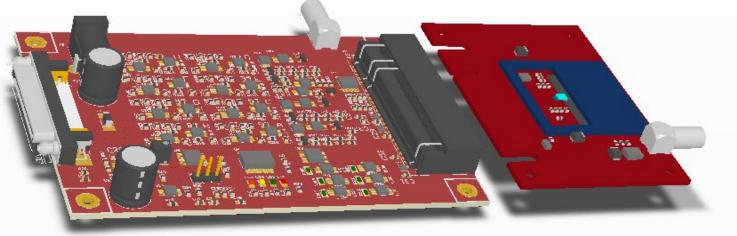
CLICpix / CCPD assembly scenario

- 1) Components cabling on CLICpix board
- 2) Components cabling on CCPD board
- 3) Merging the boards (standard soldering)
- 4) Gluing CLICpix/CCPD assembly to the CLICpix board
- 5) CLICpix wire bonding
- 6) CCPD wire bonding
- 7) Taping protection shield





CLICpix & CCPD readout status



Printed circuit boards

- Schematic
- Layout
- Documentation (user's and manufacturing)
- Manufacturing (in progress)
 - PCB production
 - Gathering components
 - Cabling (just starting) ~ 2 weeks
 - Wire bonding ~ days

Firmware/Software

- Porting old design to the IPBUS framework has started
- New components have to be developed (controlling analog parts, CCPD interface ...)



11/06/2014